

# Scaling of Sub-Micron Graphene Integrated Circuits

## Electronic Supplementary Information

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**Cutoff frequency.** The most commonly used transistor performance metric is the cutoff frequency  $f_T$ ; the intrinsic  $f_T$  can be very large in graphene FETs ( $f_T \sim 400$  GHz)<sup>1,2</sup> due to large mobility in graphene, and compares favorably to that of conventional FETs.<sup>3</sup> The cutoff frequency was also found to scale as  $f_T \propto L^{-1}$  similar to conventional semiconductor FETs.<sup>1,3</sup> However, the cutoff frequency is a measure of the internal transistor transit time rather than transistor functionality at high-frequencies. This is because the cutoff frequency is obtained from the small-signal current gain measured in a circuit in which the gate is driven by a current source while the output (between the source and drain) is shorted.<sup>4</sup> Use of an input current source makes the cutoff frequency independent of the gate resistance which is one of the main limiting factors affecting high-frequency response of FETs. Similarly, the short circuit between source and drain shorts the output conductance (in the absence of the parasitic source/drain series resistances) and therefore makes the cutoff frequency independent of the extent of the drain current saturation (shorted output also does not have any practical relevance).

**Maximum frequency of oscillation.** A more realistic figure of merit is the maximum frequency of oscillation  $f_{\max}$  which represents the frequency at which the Mason's unilateral power gain<sup>5</sup> falls to unity. Since the power gain is obtained from a circuit in which the impedance of the input voltage source and the load impedance are finite,<sup>4</sup> both the gate resistance and output conductance influence the power gain and therefore  $f_{\max}$ . For this reason graphene FETs exhibit much smaller  $f_{\max}$  than other types of transistors, typically  $\sim 50$  GHz.<sup>6</sup> By comparison,  $f_{\max} > 1$  THz has been obtained both in InP high electron mobility transistors<sup>7</sup> and heterojunction bipolar transistors.<sup>8</sup> In addition,  $f_{\max}$  of graphene FETs was found to scale only weakly with the inverse gate length.<sup>3</sup> The maximum frequency of oscillation represents an impor-

tant benchmark because it is an invariant quantity which allows comparison of different transistor technologies and accounts for real signal amplification.<sup>5</sup> However, it suffers from the requirements for device unilateralization and impedance matching which cannot be performed in realistic circuits.

**Intrinsic gate delay.** The typical figure of merit in a large-signal regime is the intrinsic gate delay  $CV/I$  which represents the time required to increase the voltage of the gate capacitor  $C_G$  by the large-signal output voltage swing  $\Delta V$  when charged by a constant drain current  $I_D$ .<sup>9</sup>

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